

BUDGET SENSITIVE MANUAL DIE BONDER

T-4909

The **T-4909** is a manual, high quality die bonder with superior ergonomic design. As with all of Tresky's products, the **T-4909** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

Force controlled

True Vertical Technology™

Easy to use

MICRO ASSEMBLY

T-4909



TRESKY

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Excellent performance, ergonomically designed and high reliability makes the T-4909 ideal for small and medium volume production.

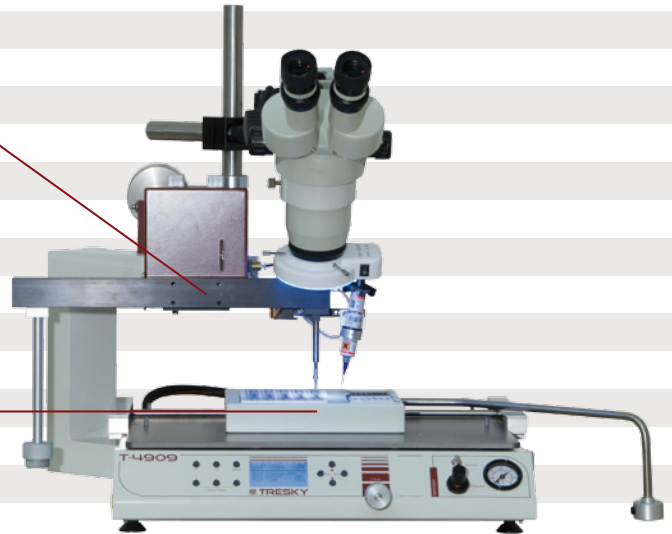
APPLICATIONS:

Die Attach, MEMS, MOEMS, VCSEL, RFID, Adhesive Bonding, Eutectic Bonding (AuAu,),

FEATURES AND OPTIONS:

- TRUE VERTICAL TECHNOLOGY™
Z-movement 60mm with 360° Tool rotation; Dispenser, Stamping, Scrub, Tool Heating, Pre Form Spindle, ...

- XY air-cushioned placement stage with micrometer control, supporting: Waffle - / Gel - Pack -, Substrate - Holder, various Heating Plates.



TECHNICAL DATA:

XY- Movement (placement stage):	180mm x 180mm (manual)
Z- Movement:	60mm (manual)
Spindle Rotation:	360°
Placement accuracy:	10µm
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	755mm x 730mm x 500mm
Weight:	30kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

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